DECLARATION - USA PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled MANUFACTURE AND CLEANING OF A SEMICONDUCTOR; the specification of which is attached hereto;

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56;

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: **Gary Chen**

Inventor's signature _____

Date 08/24/99

Residence: **2401 South Apple Street, Apt. O-104, Boise, Idaho 83706**

Citizenship: **People's Republic of China**

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Full name of second inventor: **Li Li**

Inventor's signature _____

Date 08/24/99

Residence: **2790 North Oldstone Way, Meridian, Idaho 83642**

Citizenship: **People's Republic of China**

Post Office Address: **same as above**

Full name of third inventor: Y~~~~~~~~~~

Inventor's signature _____

Date _____ 08/25/99

Residence: **2571 South Culpeper Avenue, Boise, Idaho 83709**

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